Integrated Circuit Science and Engineering

(北京理工大学 2022 版留学研究生培养方案)

(1401)

1. Overview of the Program (学科简介与研究方向)

The Integrated Circuit Science and Engineering (ICSE) discipline at Beijing Institute of Technology (BIT) has a long history that can be traced back to 1960 when the major of Semiconductor Materials and Devices was founded as one of the oldest majors in Electronics and Devices in China. Over the past 60 years, The ICSE discipline at BIT has always insisted on educating fostering high-end and urgently-needed talents for the country. In 2016, BIT was selected to establish the National Demonstration School of Microelectronics as an exemplary model; then in 2021, BIT was approved to set up a doctoral site for the discipline of Integrated Circuit Science and Engineering. This is one of the first batch of doctoral programs for this discipline in China and also the first batch of universities selected for the National Integrated Circuit Projects aiming at educating high-level talents in a short supply. The ICSE discipline at BIT focuses on the key issues in the fields of Integrated Circuits and aims to fulfill the major strategic requirements of the country as well as to lead the world frontier in science and technology. Our ICSE also persists leading to an engineering-oriented road with the combination of production and research, which may serve for the national defense in the future. This also helps to form an interdisciplinary layout with the majors of electronics, materials, information, optics, etc., as well as a joint school-enterprise training program with industry leaders such as Empyrean Technology Co., Ltd., NAURA Technology Group Co., Ltd., the 6th Research Institute of China Electronics and Piotech Inc.

There are currently 90 full-time faculty in this discipline, including 33 professors and 37 associate professors. 80% of the faculty have overseas experience. In our faculty, there are two distinguished professors entitled with "Yangtze River Scholars", two professors entitled with "Outstanding Youth", one professor honored as the technological innovation leader, one professor honored with the High-level Overseas Project, one IEEE Fellow, and six national scholars in the High-level Youth Talent Project. In addition, there are also one faculty member honored as the "Famous Teacher" and one as the "Young Famous Teacher" in Beijing.

The discipline of *Integrated Circuit Science and Engineering* has high-level laboratories such as the Key Laboratory of Low-Dimensional Quantum Structures and Devices of the Ministry of Industry and Information Technology, the Beijing Key Laboratory of Millimeter Wave and Terahertz Technology, the Beijing Engineering Technology

Research Center for Silicon-based High-speed Systems on a Chip, the National Defense Key Discipline Laboratory of Multiple Information Systems and the National Demonstration Center for Electrical and Electronics Experimental Teaching. There are also school-local cooperation institutions built together with the local governments like the BIT Chongqing Center for Microelectronics and Microsystems, the Innovation Center of MEMS/NEMS Devices and Systems (Yangtze River Delta Graduate School) and so on. Until now, the total laboratory area is nearly 10,000 square meters and the total value of experimental equipment exceeds 100 million Yuan.

The discipline undertakes scientific research projects such as the National Key R&D Projects, the projects of National Natural Science Foundation of China, the Outstanding Youth Projects, the Excellent Youth Project, the major projects of the Science and Technology Commission of the Military Commission, and key projects of the Beijing Science and Technology Plan, with an average annual research funding of over 100 million Yuan. A series of international and domestic leading achievements have been made in the fields of new low-dimensional quantum structures and devices, intelligent MEMS micromirrors, special processing chips and system applications for spaceborne signals, etc. The discipline consists of four main research directions that are described below.

1) Integrated Micro-Nano Electronics Science

Aiming at the major strategic requirements of the country in the field of Integrated Circuits, *Integrated Micro-Nano Electronics Science* carries out research on low-dimensional electronic materials, extreme bandgap semiconductor materials like ultra-wide bandgap semiconductors, as well as the device construction based on these materials, including new concept devices, power semiconductor devices, long-wavelength and solar-blind detection devices, etc. The goal is to develop intelligent, lightweight, miniaturized and multi-functional integrated extreme bandgap semiconductor functional devices, as well as provide insights into their applications in the major national strategic fields such as power transmission, new energy vehicles, high-frequency communication, and intelligent perception. The direction aims at cultivating professionals in the direction of micro-nano electronics, therefore creating a special direction of *Integrated Micro-Nano Electronics Science* in BIT, as well as promoting the discipline of Integrated Circuits and its related fields.

2) MEMS and Integrated Microsystems

MEMS and Integrated Microsystems is dedicated to the design and fabrication of MEMS micro-nano sensors and actuators as well as microfluidic chips, featuring optical MEMS, acoustic MEMS, resonant MEMS, and the integration of CMOS-MEMS. It emphasizes on the joint interdisciplines of electronics, optics, acoustics, thermal and material science, and biology, aiming to develop intelligent, multi-energy-domain, lightweight, miniaturized, and integrated microsystems with multi-functions, which can be further applied in the major national strategic fields such as intelligent sensing, intelligent manufacturing, precision medicine, unmanned driving, intelligent environmental

protection, smart robots, remote sensing, and telemetry. This direction is aimed at cultivating high-quality engineers in the fields of *MEMS and Integrated Microsystems* and promoting the development of integrated circuits as well as the related disciplines.

3) Integrated Circuit Design and Advanced Packaging

To meet the major national requirements in the fields of new-generation radar information systems, low-orbit satellite Internet, and high-efficiency signal processing, *Integrated Circuit Design and Advanced Packaging* has been focusing on the following directions: the design methods and theory of integrated circuit, the design of analog and mixed-signal integrated circuit, the design and applications of silicon-based RF/millimeter wave integrated circuit, the system-on-chip (SOC) design. Aiming at major scientific issues such as new design theories, new functional devices, and new micro-nano systems for integrated circuits in the post-Moore era, the direction have been dedicated to the fields of three-dimensional vertical interconnection technology, transition board and heterogeneous integration technology, sensor-memory-computing integrated design technology, as well as basic and applied research on new forms of information devices. The goal is to feature advantages in the fields of millimeter-wave ASIC design, through-silicon via (TSV) complete process with small diameter, ultra-high aspect ratio and ultra-high depth, ultra-large-scale special signal processing chip design and application, special anti-irradiation chips for aerospace applications, etc.

4) Flexible Electronic Devices and Intelligent Manufacturing

Aiming at multiple bottlenecks faced by flexible electronic devices in terms of structure design, preparation of semiconductor materials, large-scale manufacturing technologies and development of special equipment, etc., *Flexible Electronic Devices and Intelligent Manufacturing* is dedicated to develop new structures, new functional devices and systems in the post-Moore era. Through the in-depth interdiscipline of microelectronics, optoelectronics, quantum information, materials, mechanics, biomedicine, and artificial intelligence, etc., this direction aims to develop flexible intelligent robot perception (vision, touch, smell), bionic sensors and systems for precision medicine and personalized physiotherapy, as well as multifunctional flexible and wearable electronic systems. The goal is to cultivate professionals in the field of flexible electronics with an international perspective, and to develop Integrated Circuits and its related disciplines.

2. Training Target(培养目标)

To train students to understand the solid basic theory and systematic and specialized knowledge of the discipline, learn the modern experimental methods and skills of the discipline (direction), have an interdisciplinary academic background, and have the ability to engage in scientific research work or independently undertake specialized technical work in the field of Integrated Circuit Science and Engineering.

2) To train high-level, innovative talents who have a good knowledge of international common sense, with the ability of spreading Chinese and foreign cultures occupied, so that to bring international graduate students into full play as a cultural bridge.

3. Length of Schooling (学制)

- 1) The basic length for master students is 2 years. In principle, students must complete the courses in the first academic year. Thesis work time must be at least one year. The maximum length of study for master students can be extended by 0.5 years on the basis of 2 years.
- 2) The basic length for Ph.D. students is 4 years. In principle, students must complete the courses in the first academic year. Thesis work time must be at least three years. The maximum length of study for Ph.D. students can be extended by 2 years at maximum on the basis of 4 years.

4. Curriculum and Credits Requirements (课程设置与学分要求)

Course Classification 类别	Course Code 课程代码	Course Name 课程名称	Course Hours 学时	Credits 学分	Semester 学期	Compulsory/ Optional 是否必修	Master /Ph.D. 课程 层次	Credits Requirement 学分要求
	3700005	Chinese Language I 基础汉语 I	96	6	1	Compulsory 必修	Master /Ph.D. 硕博	Master=14 Ph.D.=14 硕士=14 博士=14
Public Courses 公共课	3700006	Chinese Language II 基础汉语 II	96	6	2	Compulsory 必修	Master /Ph.D. 硕博	
37	3700002	Outline of China 中国概况	32	2	1/2	Compulsory 必修	Master /Ph.D. 硕博	MTI
	1701002	Matrix Analysis 矩阵分析	32	2	1/2	Optional 选修	Master /Ph.D. 硕博	
Basic Courses 基础课	1701003	Science and Engineering Calculation 科学与工程计算	32	2	1/2	Optional 选修	Master /Ph.D. 硕博	Master≥2 Ph.D.≥2 硕士≥2 博士≥2
	1701007	Modern Regression Techniques in Data Sciences 现代回归方法	32	2	1/2	Optional 选修	Master /Ph.D. 硕博	
Discipline Core Courses 学科核心课	1301004	Fundamentals of MEMS Transducers MEMS 原理	32	2	1	Optional 选修	Master /Ph.D. 硕博	Master≥2 Ph.D.≥2 硕士≥2

Beijing Institute of Technology

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Artificial Intelligence

医学图像处理与人工 智能

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选修

硕士

Graduate Program 2022 Program Name: Integrated Circuit Science and Engineering Program Code: 1401 博士≥2 Microfabrication for Master Optional 1301005 IC and MEMS I 32 2 1 /Ph.D. 选修 集成电路工艺 I 硕博 Nano-Electronic Master Optional Devices and /Ph.D. 1301006 32 2 1 选修 **Applications** 硕博 纳米电子器件及应用 Modern Antenna Theory and Optional Master 0501004 2 32 2 选修 硕士 Technology 现代天线理论与技术 RF Circuit Design Theory and Optional Master 0501005 Application 32 2 2 选修 硕士 射频电路设计理论与 应用 Foundation of FPGA and SoPC Design Optional Master 0501009 2 2 32 FPGA与 SoPC 设计 选修 硕士 基础 Multi-source Data Fusion Theory and Master≥6 Optional Master Major Optional 0501011 2 Application 32 2 Ph.D. ≥ 2 选修 硕士 Courses 多源数据融合理论与 硕士≥6 专业选修课 应用 博士≥2 **Advanced Digital** Optional Master 0501014 Communication 32 2 1 选修 硕士 高等数字通信 Probability, Radom Process and Stochastic Geometry Optional Master 0501021 32 2 1 选修 硕士 in Engineering 概率、随机过程和随 机几何及其应用 Medical Image Processing and Optional Master

Beijing Institute of Technology Graduate Program 2022

Beijing Institute of Graduate Prog		Program Name: In	tegrated (Circuit Sc	ience and E	ngineering	Progra	am Code: 1401
	1301019	Semiconductor Optoelectronics 半导体光电子学	32	2	2	Optional 选修	Master 硕士	
	1301021	Radar remote sensing and channel modeling 微波遥感与信道建模	32	2	1	Optional 选修	Master 硕士	
	1301026	MEMS Design MEMS 设计	32	2	2	Optional 选修	Master /Ph.D. 硕博	
	1301027	Microfabrication of IC and MEMS II 集成电路工艺 II	32	2	2	Optional 选修	Master /Ph.D. 硕博	
	1301028	Introduction to Biophotonics 生物光子学	32	2	1	Optional 选修	Master /Ph.D. 硕博	
	1301029	Integrated Microsystems 智能集成微系统	32	2	2	Optional 选修	Master /Ph.D. 硕博	
	1301030	Advanced MEMS Optical MEMS MEMS 专题一光学	16	1	2	Optional 选修	Master /Ph.D. 硕博	
	1301031	Advanced MEMS Acoustic MEMS MEMS 专题一声学	16	1	2	Optional 选修	Master /Ph.D. 硕博	
	1301032	Advanced MEMS BioMEMS MEMS 专题一生物	16	1	2	Optional 选修	Master /Ph.D. 硕博	
	1301033	Advanced MEMS CMOS MEMS Integration MEMS 专题一 CMOS-MEMS 集成 技术	16	1	2	Optional 选修	Master /Ph.D. 硕博	
	1301034	Advanced MEMS Thermal MEMS MEMS 专题一热电	16	1	2	Optional 选修	Master /Ph.D. 硕博	

Graduate Program 2022		gram 2022	Program Name: Integrated Circuit Sc			hence and Engineering		Program Code: 1401	
		1301035	Advanced MEMS Inertial MEMS MEMS 专题一惯性	16	1	2	Optional 选修	Master /Ph.D. 硕博	
		1301036	Advanced MEMS Resonant MEMS MEMS 专题一谐振	16	1	2	Optional 选修	Master /Ph.D. 硕博	
	Total Credits		Master≥24 credits		edits	Ph.D.≥20) credits		
	合计	硕士≥24			博士≥20				

Notes (说明):

1). Public Courses

- (1) Chines Language: Set by International Students Center of BIT. All international students must take this required course.
- (2) Outline of China: Set by International Students Center of BIT. All international students must take this required course.

2) Basic Courses

If the mathematic courses listed in the chart can't meet the requirement, different Programs can set their own Basic Course.

3) Discipline Core Courses

Different Programs can set their own Discipline Core Course.

4) Major Optional Courses

International students should choose course from their own program or from other programs. Under the guidance of the supervisor, Master international students can take undergraduate courses if needed. Ph.D. international students can take undergraduate courses if needed.

说明:

1) 公共课

- (1) 汉语:由留学生中心开设,所有留学生必修课。
- (2) 中国概况:由留学生中心开设,所有留学生必修课。

2) 基础课

表中所列数学类课程若不能满足本学科对基础课要求,可另行制定其他相关的数学、物理、化学、生物、管理、人文类等学科基础课。

3) 专业课

(1) 专业核心课: 各学科确定本学科的全英文核心课程。

(2)专业选修课:可在本学科培养方案或全校专业课程库中选修。在导师指导下,留学硕士生根据需要可选修本科生课程,学分按照本科课程学分的一半计算;留学博士生根据需要可选修硕士生课程,学分按照硕士课程学分计算,但不计入博士培养计划要求学分。

5. Practice Part(实践环节)

1) Academic Activity (1 credits) 学术活动(1 学分)

International Graduate Students need to participate in academic activities, academic lectures and academic conferences of their own fields. Giving oral speeches on academic conferences, whether on or off campus, are highly recommended.

研究生在校期间参加重要的学术活动、学术讲座以及国内外学术会议等。鼓励留学生在校内外的各类学术会议上做报告。

2) Innovation Practice (1 credits) 实践活动(1 学分)

International Graduate Students should take scientific research training and social practices during their training period, which should be carried-out and evaluated by supervisors.

由指导教师指导研究生进行科研技能训练、社会实践及创新能力培养并负责考核。

6. The Dissertation Related Work(培养环节及学位论文相关工作)

1. 文献综述与开题报告; 2. 中期检查; 3. 博士论文预答辩; 4. 论文答辩; 5. 学位申请。

本学科对符合要求的硕士学位申请人和博士学位申请人分别授予交叉学科硕士和交叉学科博士学位(授位类型以国务院学位委员会正式公布为准)。

具体要求见《北京理工大学留学研究生培养环节实施细则》、《北京理工大学博士学位论文预答辩细则》以及《北京理工大学学位授予工作细则》。

Literature Review & Opening Report;
 Mid-Term Evaluation;
 Dissertation Writing and Dissertation
 Pre-Defense (for Ph.D. students);
 Thesis Defense;
 Degree Conferment

More Details can be found in Regulations of Training Procedures for International Graduates of BIT, Regulations of Dissertation Pre-Defense for Ph.D. Students of BIT and Implementation Regulations on Academic Degree Conferrals of Beijing Institute of Technology.

Time nodes of relevant procedure(相关环节时间节点要求)

The Dissertation Related Work	Master	Ph.D.
学位论文相关工作	硕士	博士

	Tume visited on the selection and Engineering 110gram court 110gram						
Literature Review& Opening Report 文献综述与开题报告	Before week 1 of the 3 rd semester 第三学期第一周(含)前	Before week 1 of the 5 th semester 第五学期第一周(含)前					
Mid-Term Evaluation 中期检查		Before week 1 of the 7 th semester 第七学期第一周前					
Dissertation Pre-Defense 论文预答辩		Before Review 论文评阅送审前完成					
Dissertation Defense 论文答辩	At least 9 months after the Opening Report 距离开题至少 9 个月	At least 18 months after the Opening Report 距离开题至少 18 个月					
Degree Application 学位申请	The application should be raised in a certain time after the Dissertation Defense 答辩后在规定时间内提出申请						

7. Course Syllabus(课程大纲)

Course Code, Course Name, Class Hour, Credits, Course Description and Course Target, Teaching Method, Evaluation and Exams, Suitable Specialty, Prerequisites, Course Contents, Reference.

所有课程教学大纲。内容包括课程编码、课程名称、学时、学分、教学目标、教学方式、考核方式、 适用学科专业、先修课程、主要教学内容和学时分配、参考文献等。